

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10776203			
<b>Filing Date:</b>	12-Feb-2004			
<b>Title of Invention:</b>	METHOD & APPARATUS FOR MULTI-STAGE SPUTTER DEPOSITION OF UNIFORM THICKNESS LAYERS			
<b>First Named Inventor/Applicant Name:</b>	Rajiv Yadav Ranjan			
<b>Filer:</b>	Anthony C. Murabito/Donna Petford			
<b>Attorney Docket Number:</b>	SEAG-STL-3394			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1810